THROUGH-HOLE LOW PROFILE HEADE

(2.00 mm) .0787" PITCH • TMM SERIES





TMM Board Mates:

CLT, SQT, SQW, ESQT, TLE, SMM, MMS

Cable Mates:

TCSD

SPECIFICATIONS

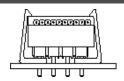
Insulator Material: Black Liquid Crystal Polymer
Terminal Material: Phosphor Bronze Plating: Sn or Au over 50 μ" (1.27 μm) Ni **Operating Temp Range:** -55 °C to +105 °C with Tin; -55 °C to +125 °C with Gold

Current Rating (SMM/TMM): 3.3 A per pin (2 pins powered) Voltage Rating: 281 VAC/397 VDC mated with SQW; 250 VAC/354 VDC mated with SQT 375 VAC/530 VDC mated with SMM

PROCESSING

Lead-Free Solderable:

APPLICATION



Retention Clip Option (-RC)

ALSO AVAILABLE

Other Platings



Some lengths, styles and options are non-standard, non-returnable.



NO. PINS PER ROW

02 thru 50

LEAD **STYLE**

Specify LEAD **STYLE** from chart

-RA & -RE

OPTION

-RA

D

(1.27)

.050

(3.56)

.140

PLATING OPTION

= Gold flash on post, Matte Tin on tail

= 10 μ" (0.25 μm) Gold on post, Matte Tin on tail

> -Т = Matte Tin

ROW **OPTION**

-S = Single Row

> -D = Double Row

> > Q-= Four Row

OPTION

-RE = Right-angle (Lead Style –01 only) (2 positions minimum, -Q row)

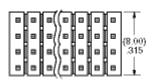
-RA &

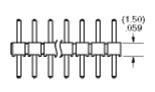
-RC = Retention Clip (Mates with TCSD) (Double row only, 4 positions minimum, only available –06 lead style)

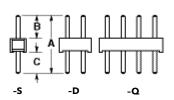
-"XXX" = Polarized Position (Specify position of omitted pin)

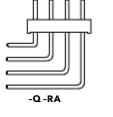












1			-
		ľ	
	-1	RC	

LEAD STYLE	A	В	с	
-01	(8.20) .323	(3.20) .126	(3.50) .138	
-02		(3.70) .146	(3.00) .118	
-03		(4.00) .158	(2.70) .106	
-04	(5.69) .224	(1.91) .075	(2.29)	
-05	(5.43) .214	(1.65) .065	.090	
-06	(9.58) .377	(3.20) .126	(4.88) .192	